DOM N. I	201612000			DON	_		D 12 2016
PCN Number:	20161209001		PCN	PCN Date:		Dec. 13, 2016	
Title: Datasheet for	· LM3405A						
<b>Customer Contact:</b>	PCN Manager				Dej	ot:	Quality Services
Change Type:							
Assembly Site		Desi	gn			Wafer	Bump Site
Assembly Process		✓ Data	Sheet			Wafer	Bump Material
Assembly Materials		Part	number change			Wafer	Bump Process
Mechanical Specification		Test	Site			Wafer	Fab Site
Packing/Shipping/Labeling		Test	Process			Wafer	Fab Materials
						Wafer	Fab Process
	No	otifica	tion Details				
<b>Description of Change:</b>							
Texas Instruments Incorp	orated is anno	uncing	an information of	only n	otifi	cation	etc.
The product datasheet(s)	is being updat	ed as s	ummarized belo	w.			
The following change hist	ory provides fu	urther o	letails.				
TEXAS							
INSTRUMENTS							LM3405A
			SNVS508D - OCT	TOBER 20	07-RE\	/ISED SEPT	EMBER 2016
Changes from Davision C (May 2	2012) to Davision D						Dage
Changes from Revision C (May 2	-						Page
<ul> <li>Added ESD Ratings table, Fea</li> </ul>							
section, Power Supply Recomm Mechanical, Packaging, and O		•				•	
Changed R <sub>BJA</sub> for SOT package							
Changed R <sub>8JA</sub> for MSOP package from 73°C/W to 55.3°C/W							
The datasheet number wi	ll be changing.						
Device Family			ange From:		CI	nange To:	
LM3405A			VS508C			NVS508D	
	<b>.</b>						
These changes may be re	viewed at the	datash	et links provide	Н			
http://www.ti.com/produc		aacasii	see mins provide	u.			
<u></u>	<u> </u>						
Reason for Change:							
To more accurately reflect	t device charac	cteristic	S.				
Anticipated impact on I				iahili	tv (	nositiv	re / negative):
	ic ic a chacitica						
No anticipated impact. Th	is is a specifica	ac.o c.	larige ariiroarieei	iiciic	····,		s are no changes to
	is is a specifica	201011 01	ange announce	meme	o,		
No anticipated impact. Th the actual device.							and no dilanges to
No anticipated impact. The the actual device.  Changes to product ide							
No anticipated impact. The the actual device.  Changes to product ide  None.							
No anticipated impact. The the actual device.  Changes to product ide None.  Product Affected:	ntification re	esulting	g from this PCN	N:			
No anticipated impact. The the actual device.  Changes to product ide None.  Product Affected:		esulting		N:			XMY/NOPB

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com